# **MA2SV04**

### Silicon epitaxial planar type

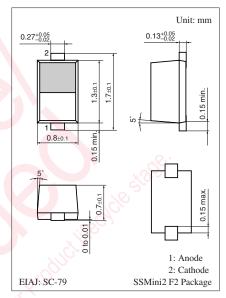
#### For VCO

#### Features

- $\bullet$  Good linearity and large capacitance-ratio in  $C_D$   $V_R$  relation
- Small series resistance r<sub>D</sub>
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	VR	6	V	
Junction temperature	Tj	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



Marking Symbol: 5

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Reverse current		IR	$V_R = 5 V$	00	SOL	10	nA
Diode capacitance		C <sub>D(1V)</sub>	$V_R = 1 V, f = 1 MHz$	10.0	0-	11.1	pF
	ċ	C <sub>D(3V)</sub>	$V_R = 3 V, f = 1 MHz$	5.8		6.4	
Series resistance *		r <sub>D</sub>	$V_{R} = 3 V, f = 470 MHz$			0.35	Ω

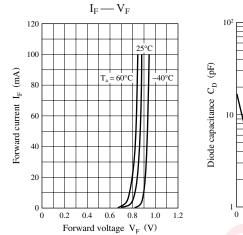
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

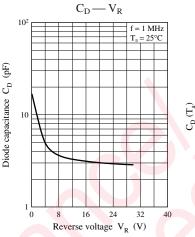
2. Absolute frequency of input and output is 470 MHz.

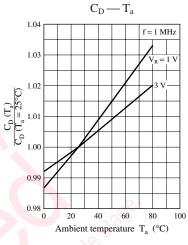
3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

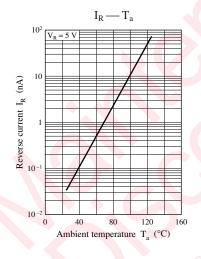
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